



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Akram

Serial No: 09/733,418 ✓

Filed: 12/08/00 ✓

For: **DEVICE ISOLATION FOR
SEMICONDUCTOR DEVICES** ✓

) Docket Number: 96-0841.01

) Paper No.: 13

) Art Unit: 2815

) Examiner: Brock II, P. ✓

Commissioner for Patents
Washington, D.C. 20231

Certificate of Mailing (37 C.F.R. §1.8)

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail, postage prepaid, in an envelope addressed to: Commissioner for Patents, Washington, 20231, on the date below:

12/16/02

Date

Signature

Dear Commissioner:

REPLY AND AMENDMENT UNDER 37 CFR §1.116

This paper is in response to outstanding Office Action dated 09/16/2002 and designated as paper no. 12.

In the Claims:

Claims 25, 30, 31, 34, 37, 38, 40, 50, 53 and 54 have been amended as rewritten below.

25. (Three Times Amended) A process for forming device isolation for a semiconductor assembly, said process comprising the steps of:

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